

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	2	"6274924".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:13
2	BRS	3815	LED adj chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:13
3	BRS	465	LED adj chip and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:33
4	BRS	981	LED adj chip same (wire wires wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:15
5	BRS	202	LED adj chip same (wire wires wiring) and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:15
6	BRS	88	LED adj chip and lead adj frame and (bent bend bending)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:17
7	BRS	32	LED adj chip and lead adj frame same metal same (plated plating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:16
8	BRS	51	LED adj chip and lead adj frame and transparent adj epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:34
9	BRS	8	LED adj chip and lead adj frame same metal same (plated plating) and transparent adj epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:23
10	BRS	19	LED adj chip same (wire wires wiring) and lead adj frame and transparent adj epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:23
11	BRS	38	LED adj chip and lead adj frame same (bent bend bending)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:30
12	BRS	29	LED adj chip and lead adj frame same pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:31

	Type	Hits	Search Text	DBs	Time Stamp
13	BRS	46	LED adj chip and lead adj frame and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:33
14	BRS	6	LED adj chip and lead adj frame and transparent adj epoxy and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 14:34
15	BRS	4	LED adj chip and lead adj frame and plating same metal and high adj reflectivity and diode and (molding mold molded) and (lead leads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 18:37
16	BRS	78	LED adj chip and lead adj frame and (bent bend bending and fold folding folded)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:18
17	BRS	8	LED adj chip and lead adj frame and plating same metal and high adj reflectivity and (molding mold molded) and (lead leads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:19
18	BRS	4	LED adj chip and lead adj frame and plating same metal and high adj reflectivity and (molding mold molded) and (lead leads) and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:20
19	BRS	29	LED adj chip and lead adj frame and plating same metal and (molding mold molded) and (lead leads) and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:20
20	BRS	324	438/26.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22
21	BRS	177	438/28.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22
22	BRS	229	438/33.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22
23	BRS	307	438/34.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22

	Type	Hits	Search Text	DBs	Time Stamp
24	BRS	86	438/35.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 16:22
25	BRS	2786	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 16:22
26	BRS	1041	438/107.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 16:22
27	BRS	492	438/112.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 16:22
28	BRS	825	438/113.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 16:22
29	BRS	0	LED adj chip and lead adj frame and Ag same Au same Pd same Mi same Cr	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:38
30	BRS	32	LED adj chip and lead adj frame same (Ag Au Pd Mi Cr)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:39
31	BRS	33	LED adj chip and lead adj frame same (Ag Au Pd Ni Cr)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:41
32	BRS	21	LED adj chip and (lead adj frame leadframe) with (Ag Au Pd Ni Cr)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:41
33	BRS	36	LED adj chip and (lead adj frame leadframe) same (Ag Au Pd Ni Cr)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:47
34	BRS	258	LED and (lead adj frame leadframe) same (Ag Au Pd Ni Cr)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:47
35	BRS	156	LED and (lead adj frame leadframe) with (Ag Au Pd Ni Cr)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:47

	Type	Hits	Search Text	DBs	Time Stamp
36	BRS	104	LED and (lead adj frame leadframe) with (Ag Au Pd Ni Cr) and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 18:47
37	BRS	53	LED and (lead adj frame leadframe) with (Ag Au Pd Ni Cr) and electrode and (bent bend bening fold folded folding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 18:48
38	BRS	57	LED and (lead adj frame leadframe) with (Ag Au Pd Ni Cr) and electrode and (bent bend bending fold folded folding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 18:48

**PALM INTRANET**

Day : Saturday

Date: 1/8/2005

Time: 15:07:17

Inventor Name Search Result

Your Search was:

Last Name = YOON

First Name = JOON HO

Application#	Patent#	Status	Date Filed	Title	Inventor Name
10617727	Not Issued	030	07/14/2003	METHOD OF MANUFACTURING LIGHT-EMITTING DIODE DEVICE	1 YOON, JOON HO

Inventor Search Completed: No Records to Display.**Search Another:
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